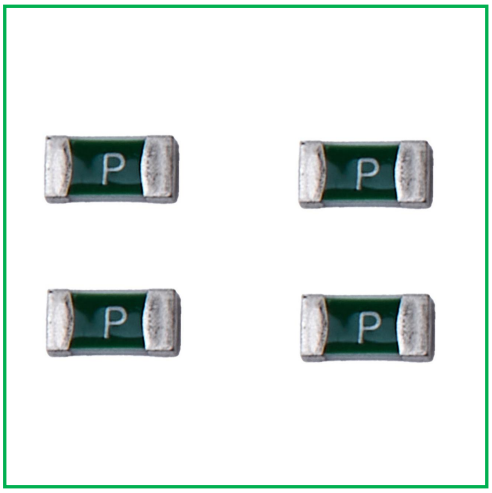
➢ Description

BSMD1206CT Series are the Time-Lag fuses set the industry standard for performance，reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our SMD fuses more heat and shock tolerant than typical subminiature fuses.



➢ Features

- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material

➢ Agency Approvals

AGENCY	AGENCY FILE NUMBER
UL	E544319

➢ Electrical Characteristics

Rated Current	1.0In	2.5In	3.0In	3.5In	10In
0.25A~0.75A	4 hour min	-	-	5 sec max	0.2~20 ms
1A~3A	4 hour min	1~60 sec	0.1~3 sec	-	0.2~20 ms
3.5A~5A	4 hour min	5 sec max	0.1~3 sec	-	0.2~10 ms
6A~8A	4 hour min	-	0.1~3 sec	5 sec max	0.2~10 ms
10A~15A	4 hour min	-	-	5 sec max	0.2~10 ms
20A	4 hour min	-	-	5 sec max	0.2~10 ms
25A~50A	4 hour min	-	0.1~3 sec	5 sec max	0.2~10 ms

➢ Part Number System

B SMD 1206 C - 1500 T

- T=Time-Lag
- AMP Code：0500=0.5A，1500=5A
- C=Ceramic
- Dimensions：1206
- SMD=Surface Mounted Devices
- B=BHFUSE

➢ Electrical Specifications

Part Number	Rated Current (A)	Rated Voltage DG	Breaking Capacity	Typical Cold. Resistance (mΩ)	Typical Voltage Drop (mV)	Typical Pre-Arcing I²t (A²sec)	Marking
BSMD1206C-0250T	0.25	72V 63V 32V 24V	50A@72VDC 50A@63VDC 150A@32VDC 300A@24VDC	3248	1267	0.00043	.25
BSMD1206C-0375T	0.375			1691	647	0.00086	E
BSMD1206C-0500T	0.50			926	583	0.0025	B
BSMD1206C-0750T	0.75			543	553	0.0061	.75
BSMD1206C-1100T	1.0			441	457	0.12	H
BSMD1206C-1125T	1.25			283	450	0.15	h
BSMD1206C-1150T	1.5			216	332	0.17	K
BSMD1206C-1200T	2.0			119	285	0.46	N
BSMD1206C-1250T	2.5			69	216	0.73	O
BSMD1206C-1300T	3.0			43	169	1.52	P
BSMD1206C-1350T	3.5			36	161	1.84	R
BSMD1206C-1400T	4.0			32	152	1.91	S
BSMD1206C-1450T	4.5	32V 24V	150A@32VDC 300A@24VDC	27	144	2.89	X
BSMD1206C-1500T	5.0			22	127	3.17	T
BSMD1206C-1600T	6.0			14	123	12.3	F
BSMD1206C-1700T	7.0			10	121	13.7	7
BSMD1206C-1800T	8.0			7.7	99	15.4	M
BSMD1206C-2100T	10			6.2	91	22.0	U
BSMD1206C-2120T	12			4.3	76	39.9	12
BSMD1206C-2150T	15			3.6	69	48.2	15
BSMD1206C-2200T	20			1.6	53	51.9	20
BSMD1206C-2250T	25			1.4	79	66.0	L
BSMD1206C-2300T	30			1.1	79	109	Z
BSMD1206C-2400T	40		200A@32VDC 200A@24VDC	0.76	86	176	XL
BSMD1206C-2500T	50			0.68	93	256	50

Notes:

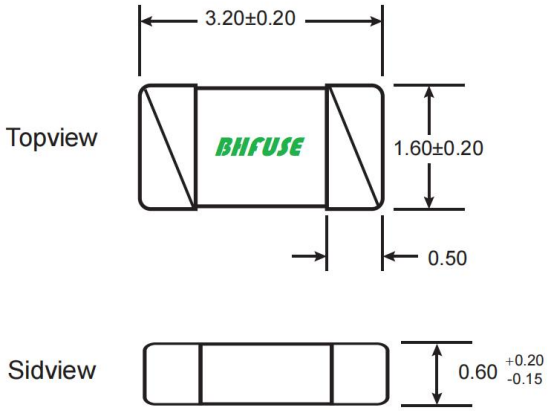
1、Typical Pre-arcing I²t are measured at 10In Current;

2、DC interrupting rating (measured at rated voltage, time constant of less than 50 microseconds, battery source) ;

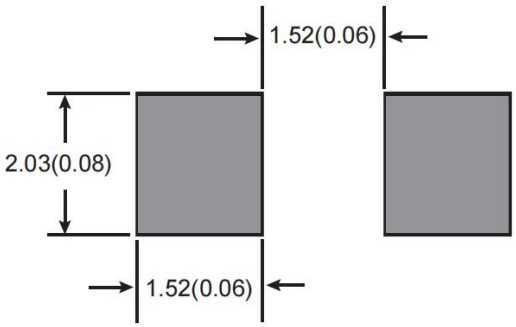
3、DC Cold resistance are measured at <10% of rated current in ambient temperature of 25°C.

➢ Dimensions

Drawing not to scale (Unit:mm/inch)

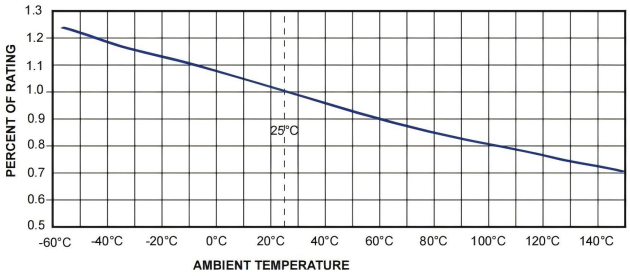


Recommended land pattern (Unit: mm/inch)

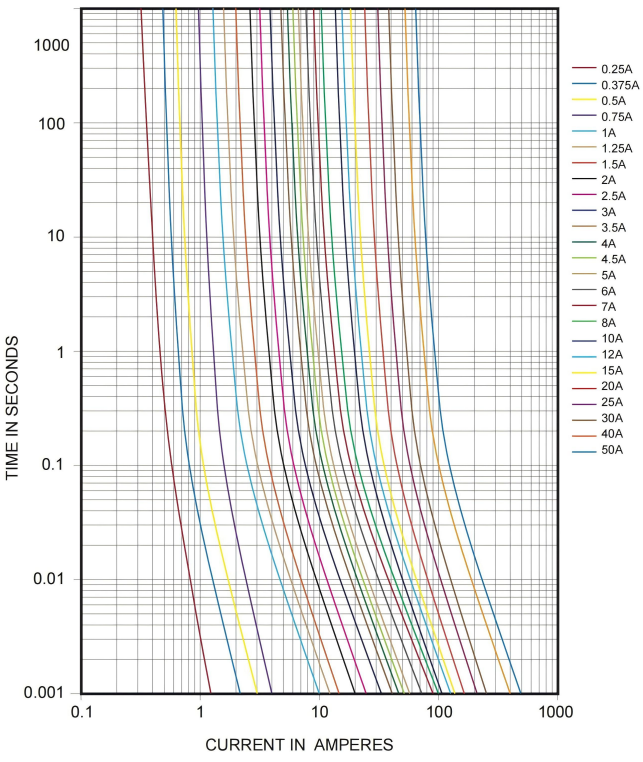


➢ Environmental Characteristic

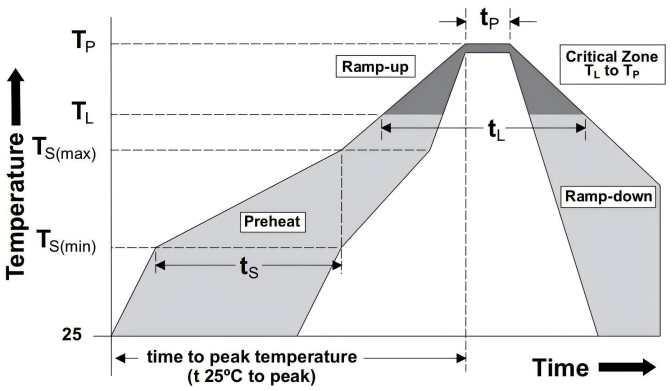
Temperature Derating Curve



Average Time-Current Curve



➢ Soldering Parameters



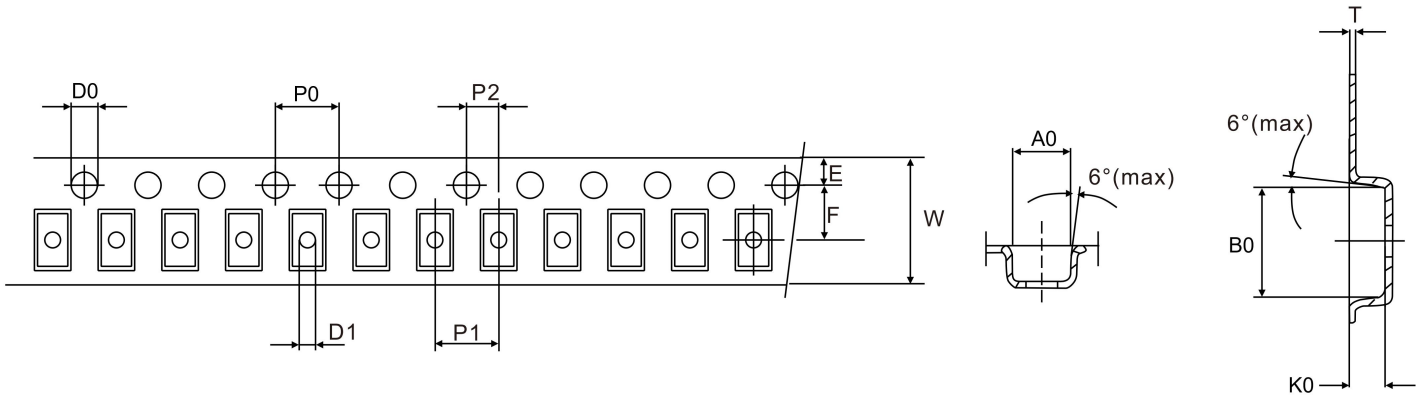
Profile Feature		Pb-Free Assembly
Average Ramp-Up Rate ($T_{s(max)}$to T_p)		3°C/sec max.
Preheat	-Temperature Min($T_{s(min)}$)	150°C
	-Temperature Max($T_{s(max)}$)	200°C
	-Time($T_{(smin)}$ to $T_{(smax)}$)	60~120 sec
Reflow	-Temperature(T_L)	217°C
	-Time(t_L)	60~150 sec
Peak Temperature (T_p)		260°C
Ramp-Down Rate		6°C/sec max.
Time 25°C to Peak Temperature		8 min max.

Notes:

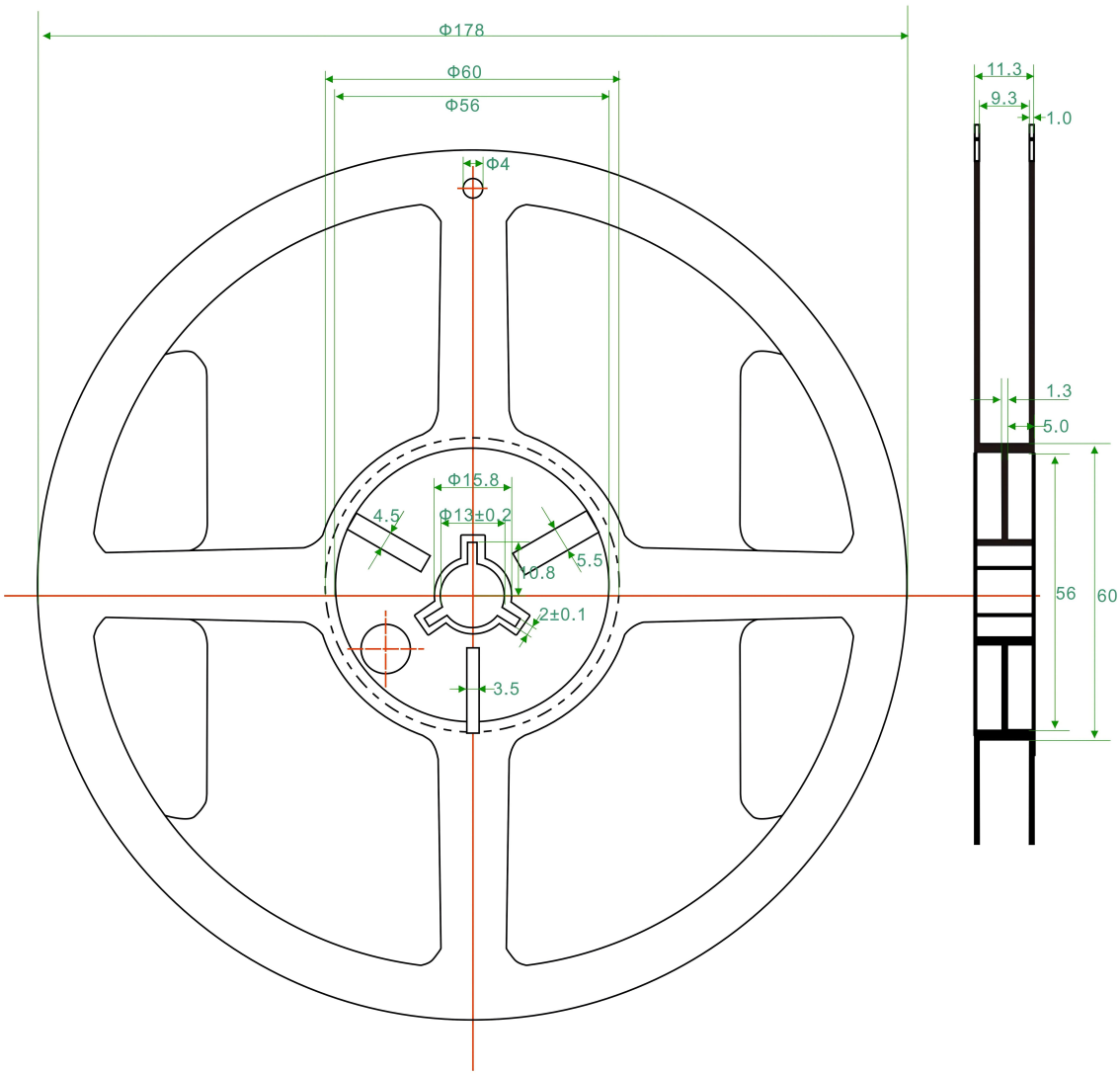
Soldering Method		Parameter
Wave Solder	Reservoir Temperature	260°C
	Time in Reservoir	10 sec max.
Infrared Reflow	Temperature	260°C
	Time	5 sec max.

1、Normal ambient temperature: 23+/-3°C ;
2、Operating temperature: -55 ~ 150°C, with proper correction factor applied.

➢ Tape And Reel Specifications (mm)



A0	1.80±0.10	B0	3.50±0.10	K0	1.27±0.10	P0	4.00±0.10	P1	4.00±0.10	P2	2.00±0.10
E	1.75±0.10	F	3.50±0.10	D0	1.50±0.10	D1	1.00 max.	W	8.00±0.10	T	0.25±0.05



➢ Packing

Part Number	Quantity & Packaging Code
BSMD1206CT Series	3000 pcs/reel 8mm tape-and-reel on a 7 inch (178mm) reel per EIA Standard 481

➢ Others

1. If in use beyond the requirements of the specifications, must pass through the mutual confirmation !

2. If the specification is not appropriate, must through consultation between the two sides and by the company to modify.

3. It could be in conformance with another file which made by our company.